



STGP19NC60W

N-channel 600V - 19A - TO-220
Ultra fast PowerMESH™ IGBT

PRELIMINARY DATA

Features

Type	V _{CES}	V _{CE(sat)} (max)@25°C	I _C @100°C
STGP19NC60W	600V	< 2.5V	22A

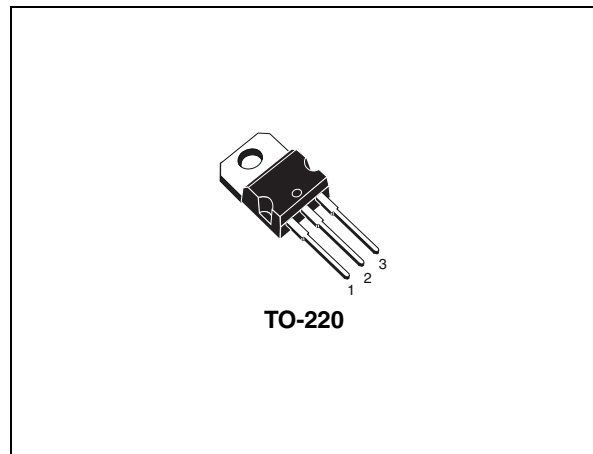
- High frequency operation
- Low C_{RES} / C_{IES} ratio (no cross-conduction susceptibility)

Description

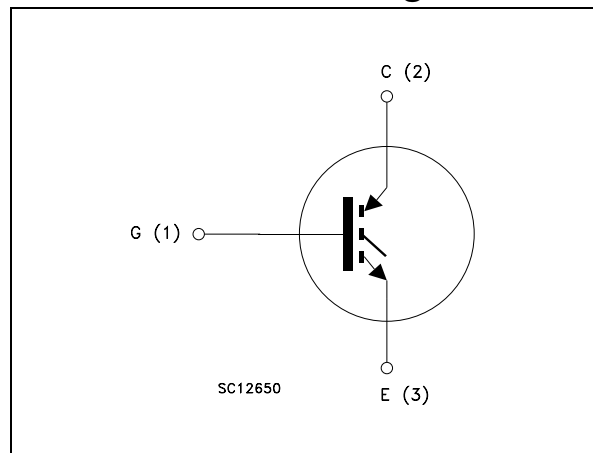
Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix “W” identifies a family optimized for very high frequency application.

Applications

- High frequency motor controls, inverters, UPS
- HF, SMPS and PFC in both hard switch and resonant topologies



Internal schematic diagram



Order code

Part number	Marking	Package	Packaging
STGP19NC60W	GP19NC60W	TO-220	Tube

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1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage ($V_{GS} = 0$)	600	V
$I_C^{(1)}$	Collector current (continuous) at $T_C = 25^\circ\text{C}$	40	A
$I_C^{(1)}$	Collector current (continuous) at $T_C = 100^\circ\text{C}$	22	A
$I_{CL}^{(2)}$	Collector current (pulsed)	35	A
V_{GE}	Gate-emitter voltage	± 20	V
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	125	W
T_{stg}	Storage temperature	- 55 to 150	$^\circ\text{C}$
T_j	Operating junction temperature		

1. Calculated according to the iterative formula::

$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \times V_{CESAT(MAX)}(T_C, I_C)}$$

2. $V_{clamp}=480\text{V}$, $T_j=150^\circ\text{C}$, $R_G=10\Omega$, $V_{GE}=15\text{V}$

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
Rthj-case	Thermal resistance junction-case max	1	$^\circ\text{C/W}$
Rthj-amb	Thermal resistance junction-ambient max	62.5	$^\circ\text{C/W}$

2 Electrical characteristics

($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Table 3. Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{BR(CES)}$	Collector-emitter breakdown voltage	$I_C = 1\text{mA}$, $V_{GE} = 0$	600			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{V}$, $I_C = 12\text{A}$ $V_{GE} = 15\text{V}$, $I_C = 12\text{A}$, $T_C = 125^{\circ}\text{C}$		2.1 1.8	2.5	V V
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$, $I_C = 250\ \mu\text{A}$	3.75		5.75	V
I_{CES}	Collector cut-off current ($V_{GE} = 0$)	$V_{CE} = \text{Max rating}$, $T_C = 25^{\circ}\text{C}$ $V_{CE} = \text{Max rating}$, $T_C = 125^{\circ}\text{C}$			150 1	μA mA
I_{GES}	Gate-emitter leakage current ($V_{CE} = 0$)	$V_{GE} = \pm 20\text{V}$, $V_{CE} = 0$			± 100	nA
g_{fs}	Forward transconductance	$V_{CE} = 15\text{V}$, $I_C = 12\text{A}$		10		S

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	$V_{CE} = 25\text{V}$, $f = 1\text{MHz}$, $V_{GE} = 0$		1180		pF
C_{oes}	Output capacitance			130		pF
C_{res}	Reverse transfer capacitance			26		pF
Q_g	Total gate charge	$V_{CE} = 390\text{V}$, $I_C = 5\text{A}$,		53		nC
Q_{ge}	Gate-emitter charge	$V_{GE} = 15\text{V}$,		10		nC
Q_{gc}	Gate-collector charge	(See figure 15)		21		nC

Table 5. Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 390V, I_C = 12A$		25		ns
t_r	Current rise time	$R_G = 10\Omega, V_{GE} = 15V,$		7		ns
$(di/dt)_{on}$	Turn-on current slope	(See figure 16)		1600		A/ μ s
$t_{d(on)}$	Turn-on delay time	$V_{CC} = 390V, I_C = 12A$		25		ns
t_r	Current rise time	$R_G = 10\Omega, V_{GE} = 15V,$		8		ns
$(di/dt)_{on}$	Turn-on current slope	$T_j = 125^\circ C$ (See figure 16)		1400		A/ μ s
$t_r(V_{off})$	Off voltage rise time	$V_{CC} = 390V, I_C = 12A$		22		ns
$t_{d(off)}$	Turn-off delay time	$R_G = 10\Omega, V_{GE} = 15V,$		90		ns
t_f	Current fall time	(See figure 16)		43		ns
$t_r(V_{off})$	Off voltage rise time	$V_{CC} = 390V, I_C = 12A$		47		ns
$t_{d(off)}$	Turn-off delay time	$R_G = 10\Omega, V_{GE} = 15V,$		127		ns
t_f	Current fall time	$T_j = 125^\circ C$ (See figure 16)		77		ns

Table 6. Switching energy (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{on}^{(1)}$	Turn-on switching losses	$V_{CC} = 390V, I_C = 12A$		81		μ J
$E_{off}^{(2)}$	Turn-off switching losses	$R_G = 10\Omega, V_{GE} = 15V,$		125		μ J
E_{ts}	Total switching losses	(See figure 16)		206		μ J
$E_{on}^{(1)}$	Turn-on switching losses	$V_{CC} = 390V, I_C = 12A$		161		μ J
$E_{off}^{(2)}$	Turn-off switching losses	$R_G = 10\Omega, V_{GE} = 15V,$		255		μ J
E_{ts}	Total switching losses	$T_j = 125^\circ C$ (See figure 16)		416		μ J

1. E_{on} is the turn-on losses when a typical diode is used in the test circuit in figure 14. If the IGBT is offered in a package with a co-pak diode, the co-pak diode is used as external diode. IGBTs & Diode are at the same temperature (25°C and 125°C)
2. Turn-off losses include also the tail of the collector current

2.1 Electrical characteristics (curves)

Figure 1. Output characteristics

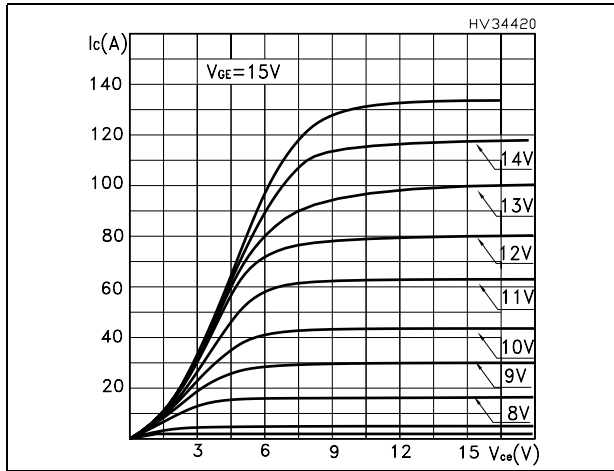


Figure 2. Transfer characteristics

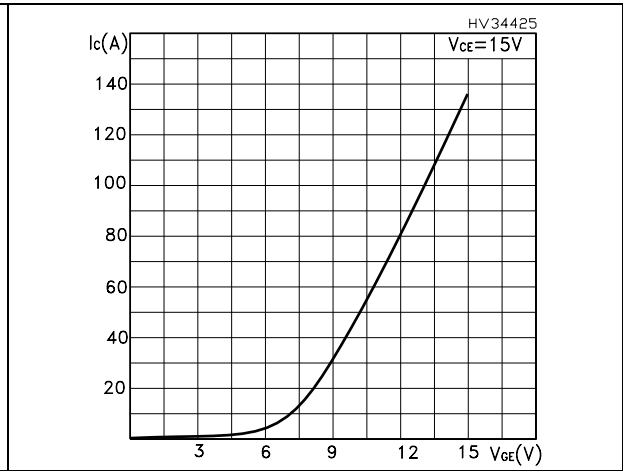


Figure 3. Transconductance

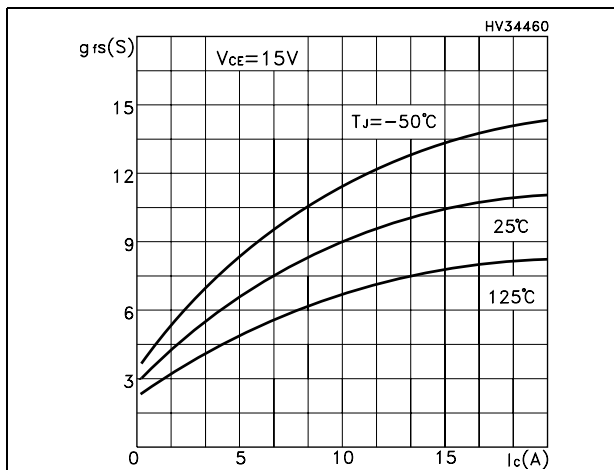


Figure 4. Collector-emitter on voltage vs temperature

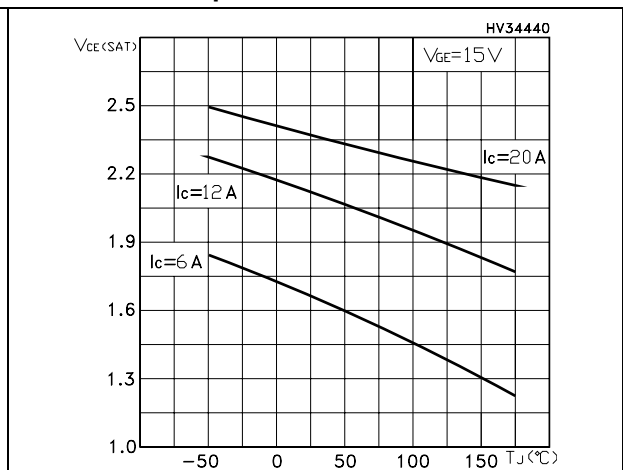


Figure 5. Gate charge vs gate-source voltage

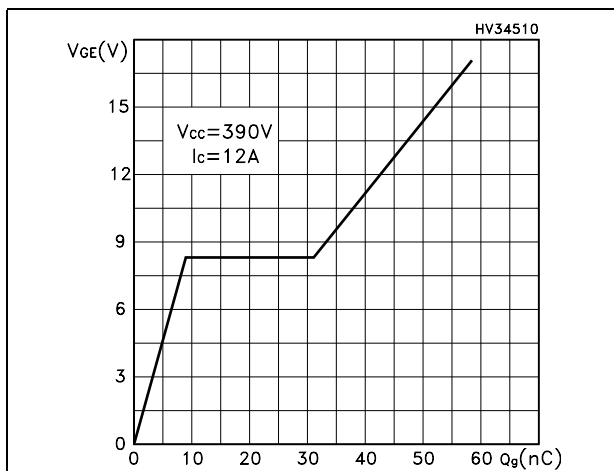


Figure 6. Capacitance variations

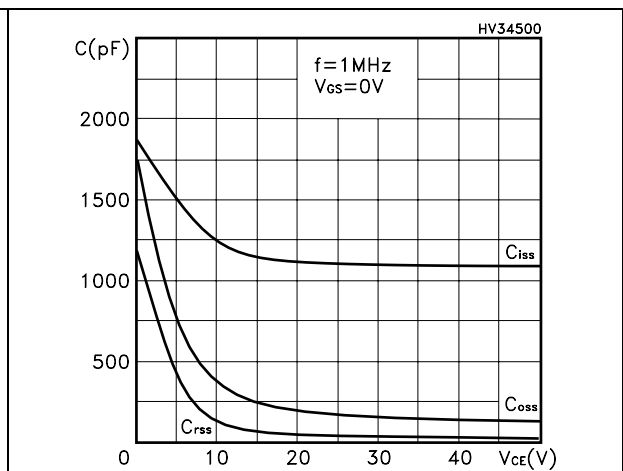


Figure 7. Normalized gate threshold voltage vs temperature

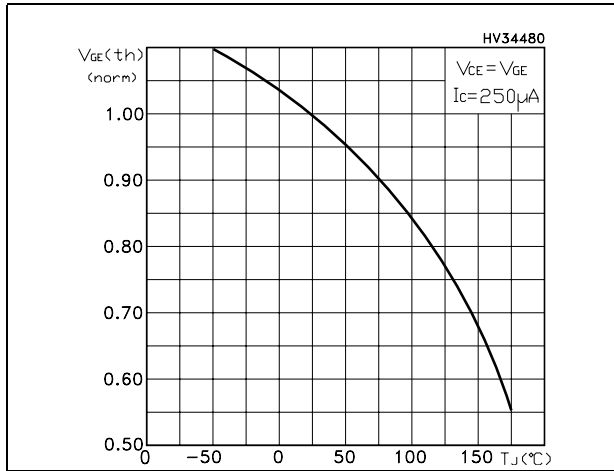


Figure 8. Collector-emitter on voltage vs collector current

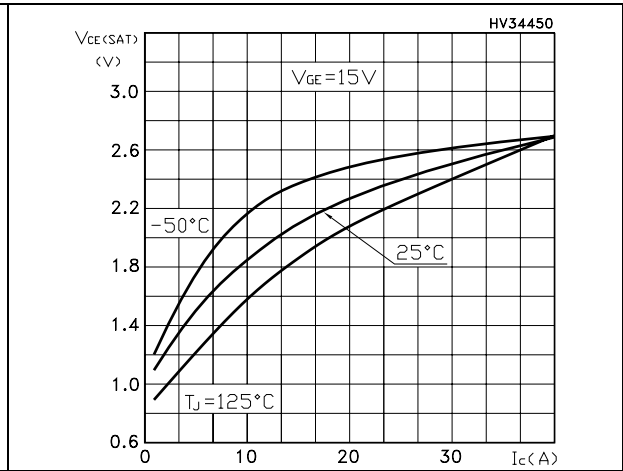


Figure 9. Normalized breakdown voltage vs temperature

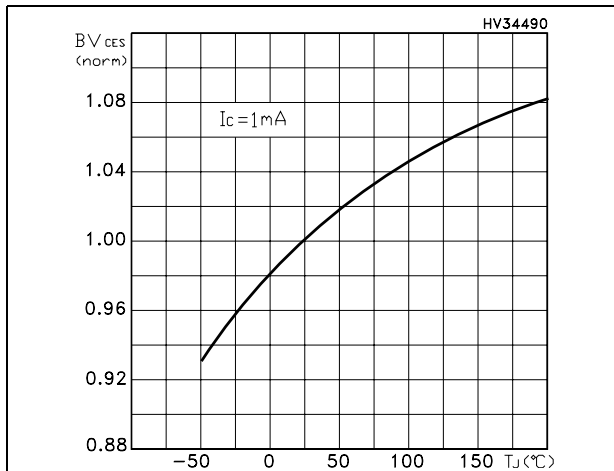


Figure 10. Switching losses vs temperature

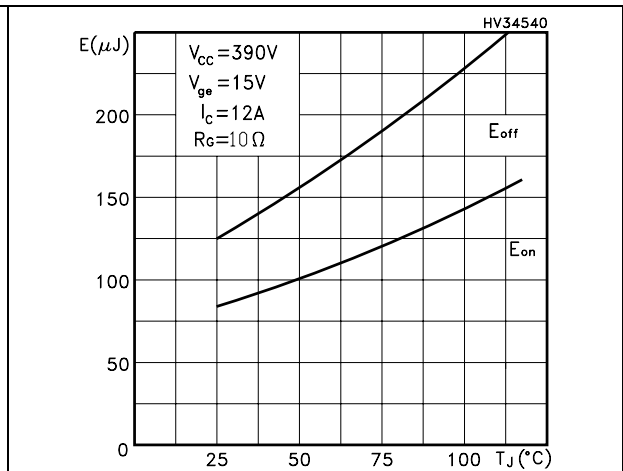


Figure 11. Switching losses vs gate resistance

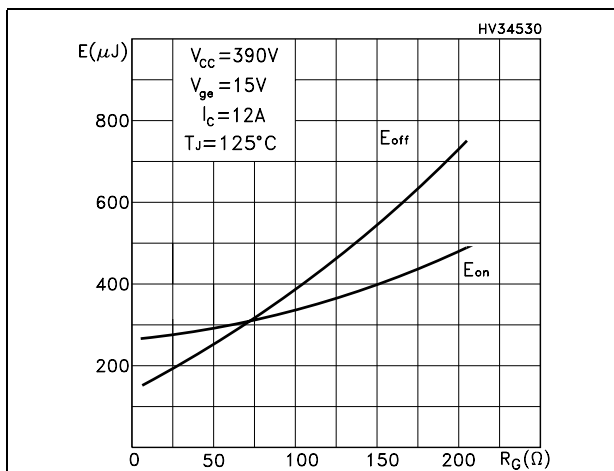


Figure 12. Switching losses vs collector current

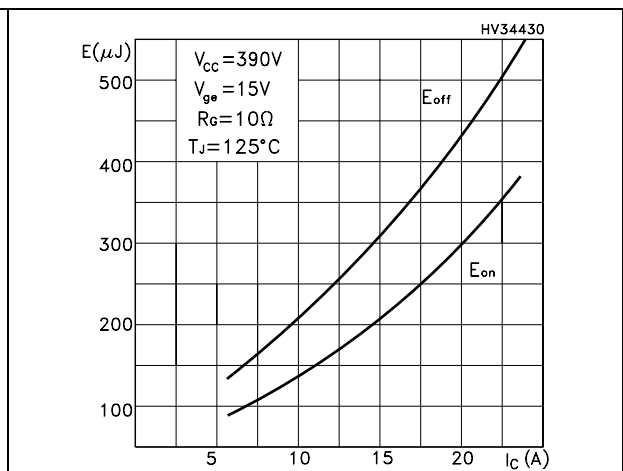
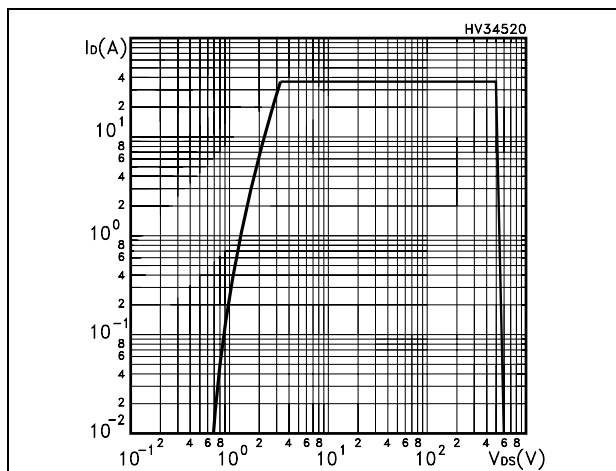


Figure 13. Turn-off SOA



3 Test circuit

Figure 14. Test circuit for inductive load switching

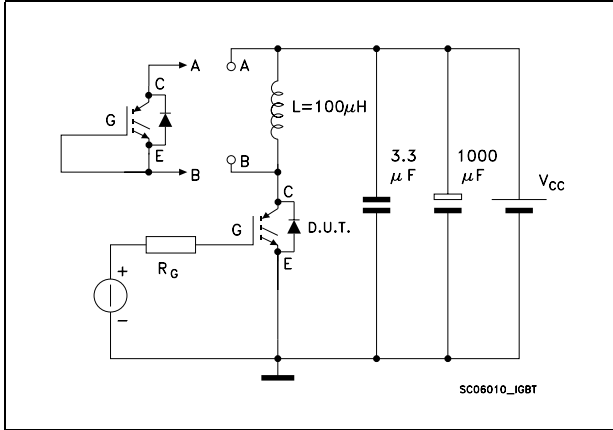


Figure 15. Gate charge test circuit

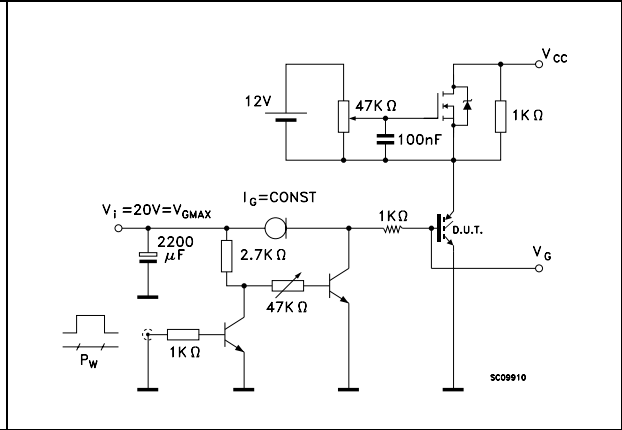
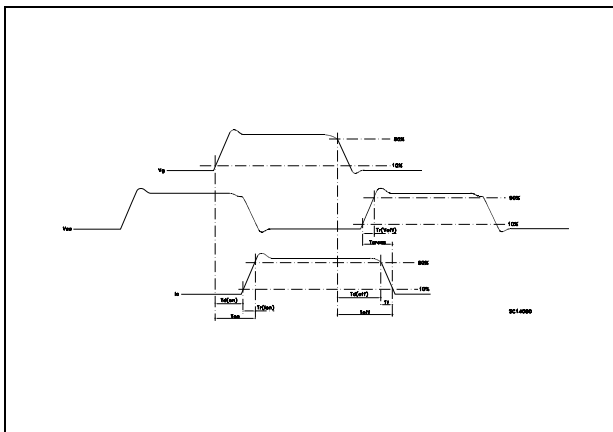


Figure 16. Switching waveform

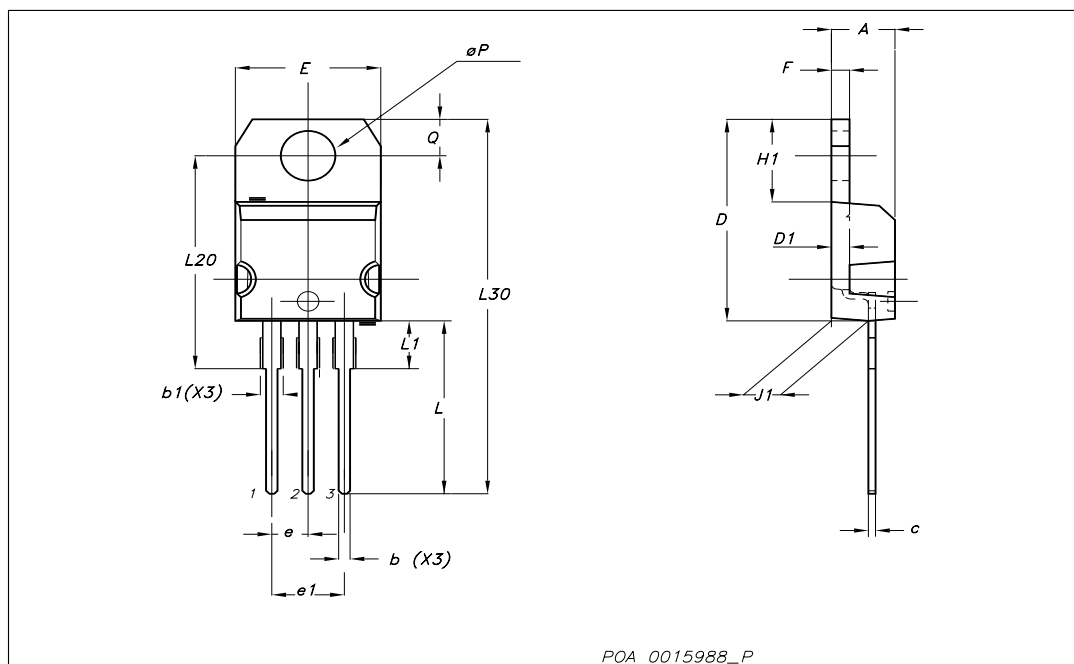


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-220 mechanical data

Dim	mm			inch		
	Min	Typ	Max	Min	Typ	Max
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.6		0.62
D1		1.27			0.050	
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.051
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
∅P	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



5 Revision history

Table 7. Revision history

Date	Revision	Changes
04-Oct-2006	1	Initial release.
08-May-2007	2	Modified vaule on Table 1

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